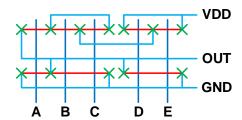
1. (a)

有多種答案,畫對任一種都算對,不用標示 size

(b)
$$g_a = \frac{6+1}{3} = \frac{7}{3}$$
 $g_c = \frac{3+2}{3} = \frac{5}{3}$ $g_d = \frac{3+2}{3} = \frac{5}{3}$

(c)



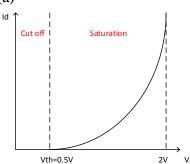
有多種答案,畫對任一種都算對,並要正確標示 A~E,VDD,GND,Y(out) 若需使用到 metal2 則需明顯標示。

(d) (2.5%) (no partial)

$$P_{\text{max}} = \frac{6+6+2+2+1}{3} = \frac{17}{3}$$

$$P_{\min} = \frac{6+2+2+1}{3} = \frac{11}{3}$$

2. (a)

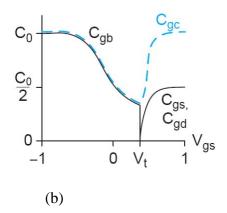


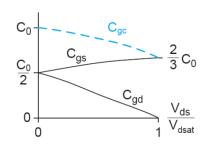
(b) at saturation: $I_D = \frac{1}{2} u_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH})^2$

at linear :
$$I_D = \frac{1}{2} u_n C_{ox} \frac{W}{L} (2(V_{GS} - V_{TH}) V_{DS} - V_{DS}^2)$$

at cut off : $I_D = 0$

3. (a)





4. (a) d=gh+p=2

$$d'=d \times R \times C = 2 \times 5k \times 10f$$

$$f_{\rm osc} = \frac{1}{2 \text{Nd'}} = \frac{1}{2 \times 5 \times 2 \times 5 \text{k} \times 10 \text{f}} = 1.0 \text{GHz or } 10^9 \text{Hz}$$

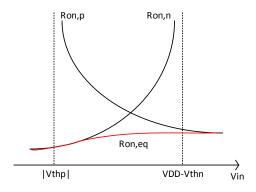
(b) Unit inverter g_{avg}=1

Skewed inverter $g_{avg} = 1$

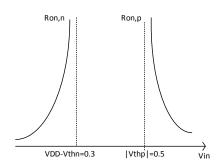
$$f_{osc} = \frac{1}{2Nd'} = \frac{1}{5 \times 2 \times 5k \times 10f} = 1.0GHz \text{ or } 10^9Hz$$

- 5. (a) 當 V_{DS} 電壓上升, D_{TA} 可以 端空乏區變大,使得有效 D_{TA} Channel length 縮短,讓 D_{DS} 上升。
 - (b) 因半導體中 Carrier 有其最大速度極限,使得當 V_{DS} 增加時,其速度並不會正比於電場大小,此時可以稱之為 Velocity Saturation,也造成 I_{DS} 因此達到飽和。
 - (c) CMOS 具有寄生 BJT 與阻值,當電流流經 Substrate 使得寄生 BJT 間產 生正回授 Loop 造成 VDD-GND 的大電流產生。
 - (d) 當 Body 與 Source 電壓不一致時,造成 Threshold 電壓改變。
 - (e) 當 Channel 電場過大,在 Carrier 上產生高能量,並撞擊矽原子產生電子電洞對,產生漏電流。

6. (a)



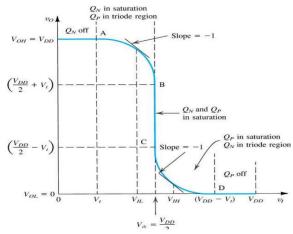
(b)



Ron 在小於 0.3 V 與大於 0.5 V 時,會隨著 vin 變動而有巨幅改變,在 0.3 V~0.5 V 時, MOS turn off , 為 high impedance

7. (a) (W/L)p = (6um/0.18um)

(b)



(c) $NM_H = VOH-VIH$

$$NM_L = VIL - VOL$$

(d) NM_H C>B>A

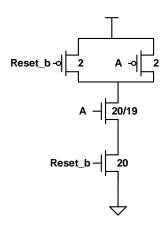
 NM_L A>B>C

8. (a)
$$D = NF^{\frac{1}{N}} + \sum_{i=1}^{n_1} P_i + (N-n_1)P_{inv}$$

(b) Pinv+
$$\rho(1-\ln\rho)=0$$
, Pinv=1, $\rho=3.59$
D = $(10\times3.59) + (4\times3) + (6\times1) = 53.9$

- 9. (a) if N=3, f=6.35, D=3×6.35+3=22.05 if N=4, f=4, D=4×4+4=20 if N=5, f=3.03, D=5×3.03+5=20.16 N=4 has the minimum delay
 - **(b)** f=4, D=4×4+4=20

10.



(a) Pull down path: resistance = $1 - \frac{1}{20} = \frac{19}{20}$; size_A = $\frac{20}{19}$

Pull up path unchanged: sizes = 2

(b)
$$g_A = \frac{2 + \frac{20}{19}}{3} = \frac{58}{57}, g_B = \frac{2 + 20}{3} = \frac{22}{3}$$

11.

$$C_{wire} = 500 fF$$

$$C_{adj} = 200 fF$$

$$R_{wire} = 0.6x (1mm/0.5um) = 1.2K$$

(a)
$$C_{eff} = 200*2+500 = 900fF$$

$$0.5k \times (50f+450f) + (0.5k+1.2k) \times 450f = 1.015ns$$

(b)
$$C_{\text{eff}} = 200*1+500 = 700 \text{fF}$$

$$0.5k \times (50f+350f) + (0.5k+1.2k)\times 350f = 795ps$$

(c)
$$\Delta V_Y = 1.8x (200f/700f) = 0.514V$$

(d) Shielding, Increase the loading Cap, Put two wire away

12. (a)
$$H = \frac{300}{3} = 100$$

F = GBH =
$$\left(1 \times \frac{4}{3} \times \frac{5}{3} \times \frac{5}{3}\right) (2 \times 2) \left(\frac{300}{3}\right) = \frac{40000}{27}$$

$$N = 4$$
, $P = 1 + 2 + 3 + 2 = 8$

$$D = NF^{\frac{1}{N}} + P = 32.82$$

(b)
$$f = \left(\frac{40000}{27}\right)^{\frac{1}{4}} = 6.204$$

$$Cin = \frac{g \times Cout}{f}$$

$$= \begin{cases} z = \frac{5/3 \times 300}{6.204} = 80.59 \\ y = \frac{5/3 \times 80.59}{6.204} = 21.65 \\ x = \frac{4/3 \times 21.65 \times 2}{6.204} = 9.305 \end{cases}$$

13.

(a)

$$gu = \frac{2}{3}, gd = \frac{2}{9}, g_{avg} = \frac{4}{9}$$

$$gu = \frac{17}{3}, pd = \frac{17}{9}, p_{avg} = \frac{34}{9}$$

$$G = 1 \times \frac{4}{9} = \frac{4}{9}$$

$$H = \frac{64}{1} = 64$$

$$F = GBH = \frac{4}{9} \times 1 \times 64 = \frac{256}{9}$$

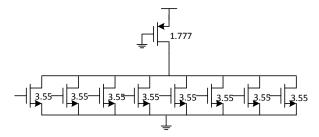
$$D = NF^{\frac{1}{N}} + P = 2 \times \sqrt{\frac{256}{9} + \frac{34}{9}} = 35.777$$

(b)
$$f = \sqrt{\frac{256}{9}} = \frac{16}{3}$$

$$x = \frac{C_{out} \times g_{in}}{f} = \frac{64 \times \frac{4}{9}}{\frac{16}{3}} = 5.3333$$

PMOS:
$$5.333 \times \frac{\frac{1}{3}}{\frac{1}{3} + \frac{2}{3}} = 1.7777$$

NMOS:
$$5.333 \times \frac{\frac{2}{3}}{\frac{1}{3} + \frac{2}{3}} = 3.5555$$



14.

Sizing:

MNOS=> 3 unit

PMOS=> 2 unit

(a)

 $T_{pdr} = (9+5h)RC$

 $T_{pdf} = (3C*R/3) + (3C*2R/3) + R*(9+5h)C = (12+5h)RC$

 $T_{pd} = (10.5 + 5h)RC$

(b)

 $T_{cdr} = R/3 *(9+5h)C = (9+5h)RC/3$

 $T_{cdf} = (9+5h)RC$

 $T_{cd} = (18+10h)RC/3$

15.

- (a) 使用 high-K dielectric 可以降低 EOT, 並降低 gate leakage
- (b) 使用 low-K dielectric 可以降低導線寄生電容
- (c) 增加導電度,降低阻值
- (d) 可以增加對 Gate 的控制能力,降低 leakage
- (e) High speed & 避免 Latch up 產生

16. FTTFT TTTFT